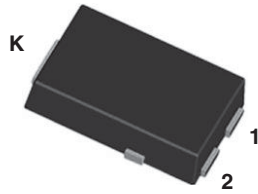
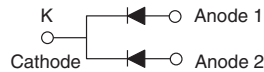


Hyperfast Rectifier, 2 x 4 A FRED Pt[®]

eSMP[®] Series

SMPC (TO-277A)

FEATURES

- Hyperfast recovery time, reduced Q_{rr} , and soft recovery
- 175 °C maximum operating junction temperature
- Specified for output and snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE
DESIGN SUPPORT TOOLS
[click logo to get started](#)
3D
 Models
 Available

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 x 4 A
V_R	200 V
V_F at I_F	0.72 V
t_{rr} (typ.)	25 ns
T_J max.	175 °C
Package	SMPC (TO-277A)
Circuit configuration	Common cathode

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, piezo-injection, as high frequency rectifiers, and freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		200	V
Average rectified forward current	$I_{F(AV)}$	$T_{Sp} = 160$ °C	per device	8
			per diode	4
Non-repetitive peak surge current	I_{FSM}	$T_J = 25$ °C	per device	130
			per diode	70
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ μ A	200	-	-	V
Forward voltage, per diode	V_F	$I_F = 4$ A	-	0.89	0.95	V
		$I_F = 4$ A, $T_J = 150$ °C	-	0.72	0.78	
Reverse leakage current, per diode	I_R	$V_R = V_R$ rated	-	-	2	μ A
		$T_J = 150$ °C, $V_R = V_R$ rated	-	6	80	
Junction capacitance	C_T	$V_R = 200$ V	-	17	-	pF

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $dI_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	25	-	ns	
		$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$	-	-	25		
		$T_J = 25\text{ }^\circ\text{C}$	-	18	-		
		$T_J = 125\text{ }^\circ\text{C}$	-	27	-		
Peak recovery current	I_{RRM}	$I_F = 4\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	2	-	A
			$T_J = 125\text{ }^\circ\text{C}$	-	3.6	-	
Reverse recovery charge	Q_{rr}		$T_J = 25\text{ }^\circ\text{C}$	-	18	-	nC
			$T_J = 125\text{ }^\circ\text{C}$	-	50	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J , T_{Stg}		-55	-	175	$^\circ\text{C}$
Thermal resistance, junction to solder pad, per leg	R_{thJ-Sp}		-	2.5	3.5	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to ambient, per leg	R_{thJA}		-	80	-	$^\circ\text{C}/\text{W}$
Approximate weight			0.1			g
			0.0035			oz.
Marking device		Case style SMPC (TO-277A)	QCH2			

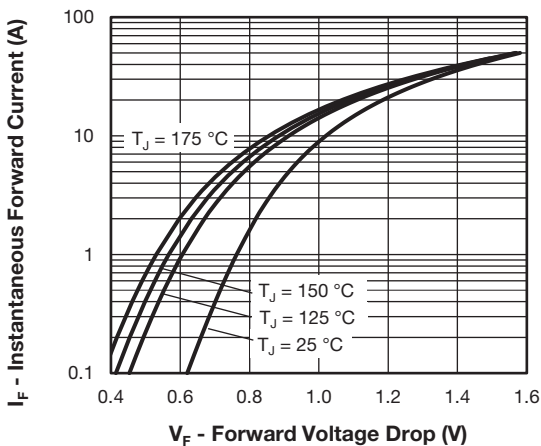


Fig. 1 - Typical Forward Voltage Drop Characteristics

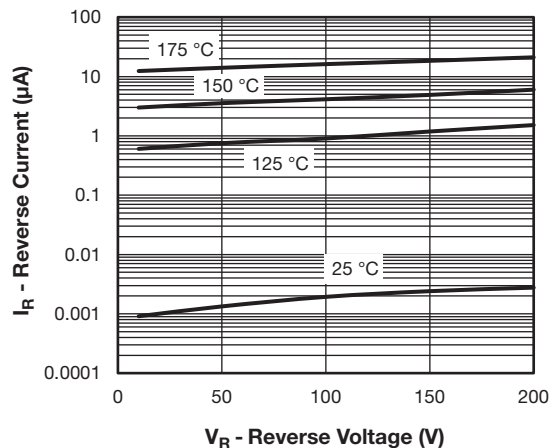


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

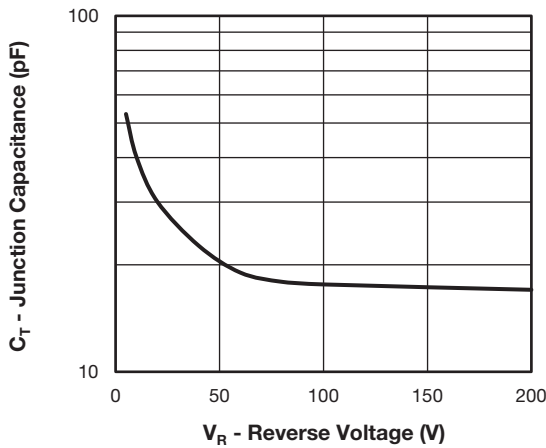


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

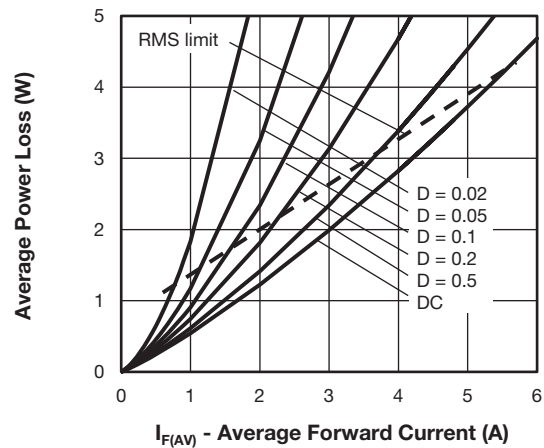


Fig. 5 - Forward Power Loss Characteristics

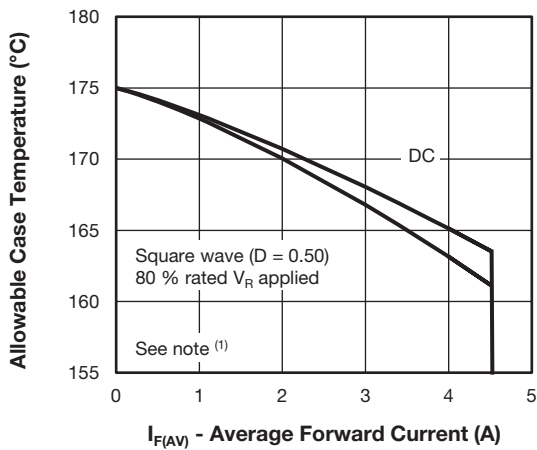


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

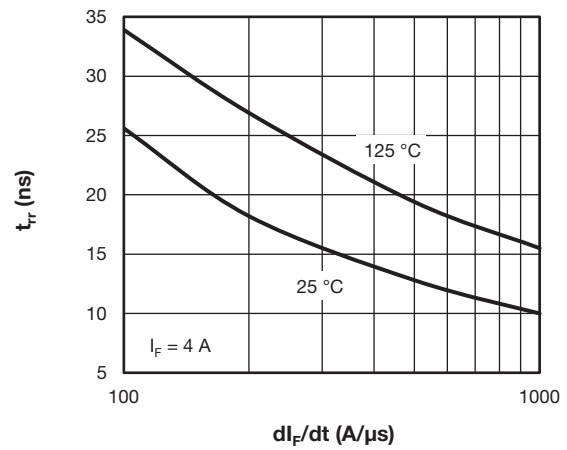


Fig. 6 - Typical Reverse Recovery Time vs. dI_F/dt

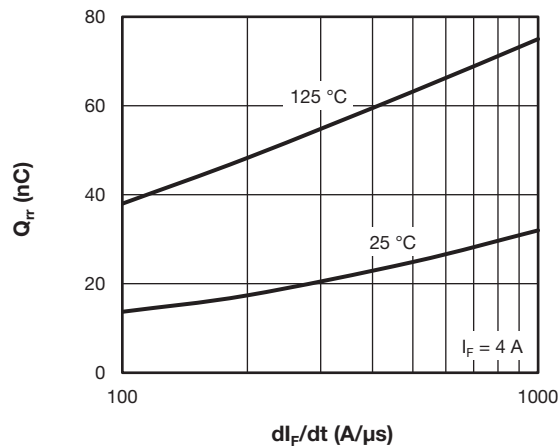


Fig. 7 - Typical Stored Charge vs. dI_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
- P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);
- P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

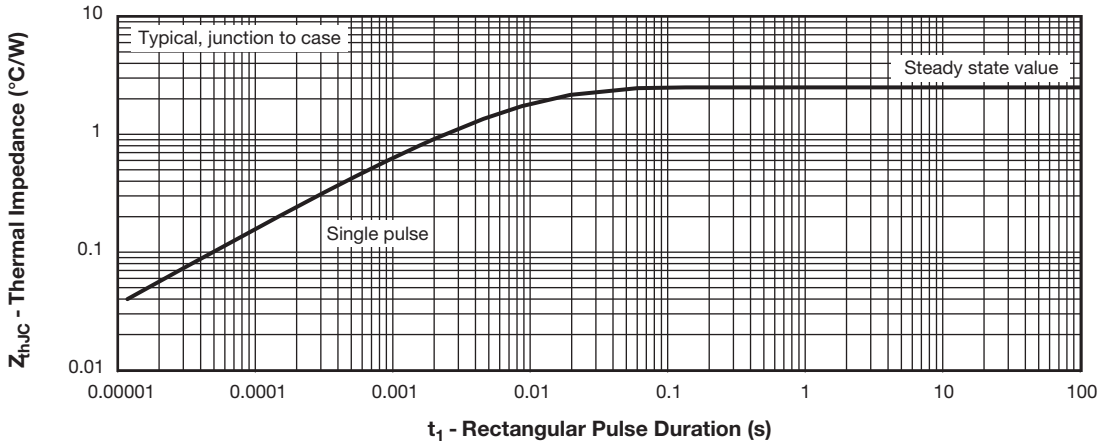


Fig. 8 - Typical Transient Thermal Impedance, Junction to Case

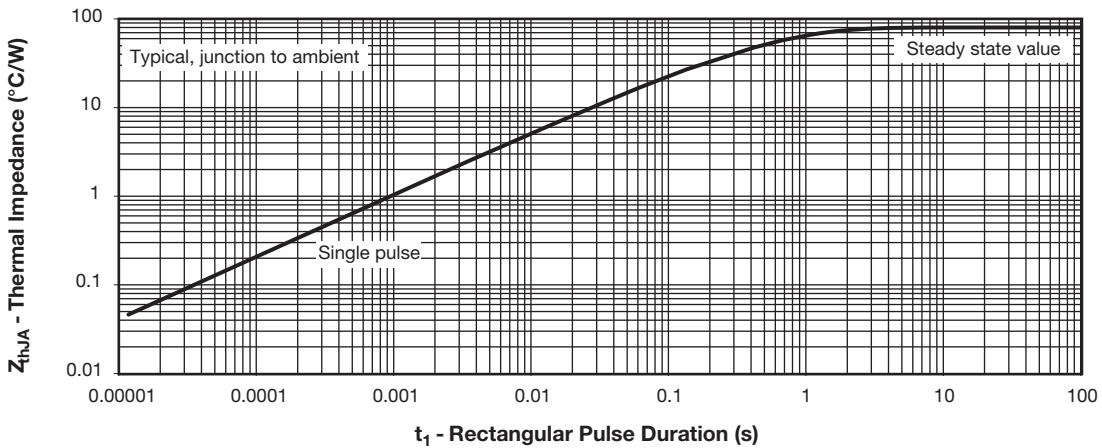


Fig. 9 - Typical Transient Thermal Impedance, Junction to Ambient

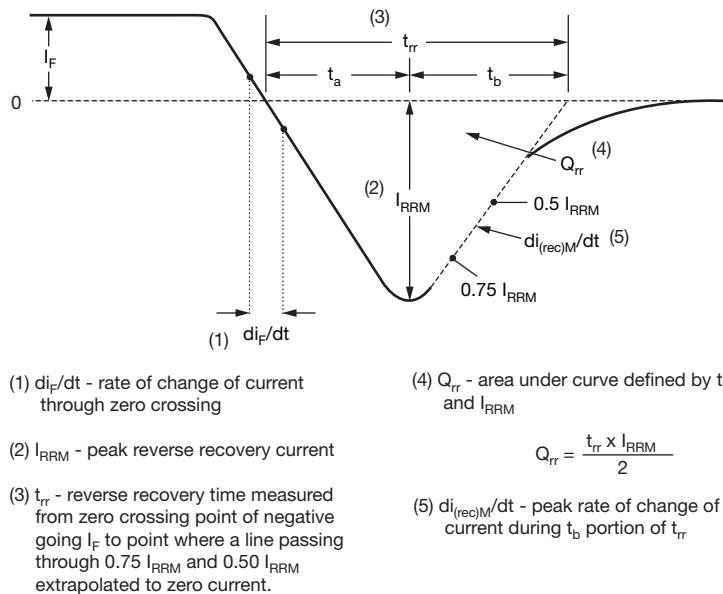
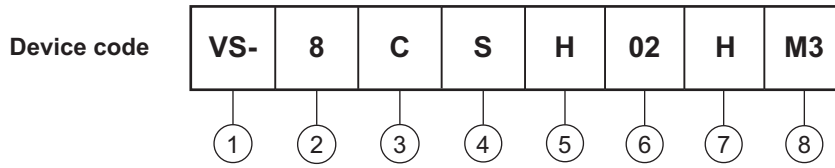


Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (8 = 8 A)
- 3** - Circuit configuration:
C = common cathode
- 4** - S = SMPC package
- 5** - Process type,
H = hyper fast recovery
- 6** - Voltage code (02 = 200 V)
- 7** - H = AEC-Q101 qualified
- 8** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

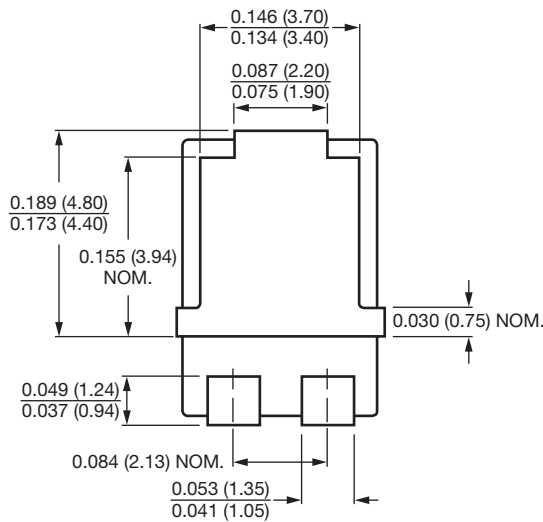
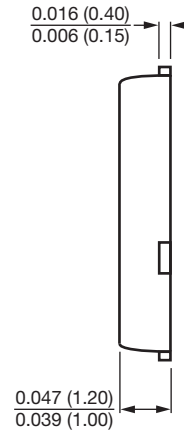
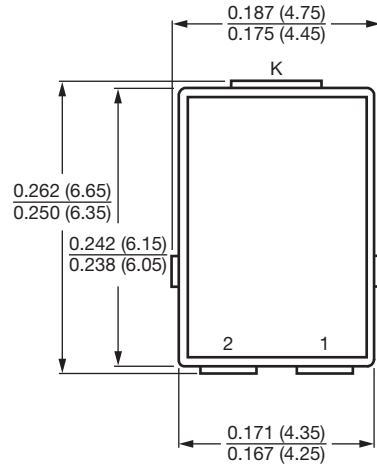
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8CSH02HM3/86A	1500	1500	7" diameter plastic tape and reel
VS-8CSH02HM3/87A	6500	6500	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95570
Part marking information	www.vishay.com/doc?95565
Packaging information	www.vishay.com/doc?88869
SPIICE model	www.vishay.com/doc?96095

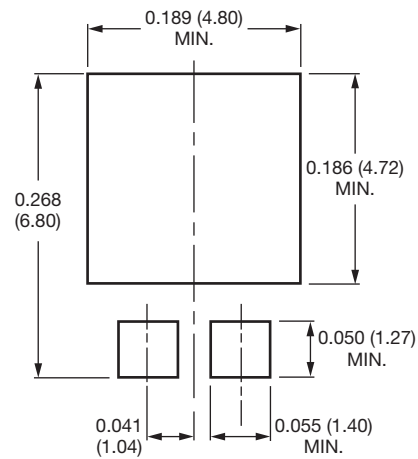


TO-277A (SMPC)

DIMENSIONS in inches (millimeters)



Mounting Pad Layout



Conform to JEDEC® TO-277A



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